

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6633583

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JUNG YONG CHAE	03/19/2021
JIN HEE CHO	03/19/2021
RECEIVING PARTY DATA	
Name:	SK HYNIX INC.
Street Address:	2091, GYEONGCHUNG-DAERO
Internal Address:	BUBAL-EUB, GYEONGGI-DO
City:	ICHEON-SI
State/Country:	KOREA, REPUBLIC OF
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17219336
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ATTORNEY DOCKET NUMBER:	088453-8381.US00
NAME OF SUBMITTER:	JAYME JONES
SIGNATURE:	/Jayme Jones/
DATE SIGNED:	03/31/2021
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 4	
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source=2021-3-31_Assignment_asfiled_088453-8381US00#page2.tif	
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Jung Yong CHAE et al.

Application No.:

Filed: Herewith

For: SEMICONDUCTOR DEVICE INCLUDING A
THROUGH SILICON VIA STRUCTURE AND
METHOD OF FABRICATING THE SAME

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

DECLARATION AND ASSIGNMENT BY THE INVENTOR
UNDER RULE 37 C.F.R. § 1.63 EFFECTIVE ON SEPTEMBER 16, 2012

I, Jung Yong CHAE et al., hereby declare that:

I believe I am the sole original inventor or an original joint inventor of a claimed invention in a patent application entitled:

**SEMICONDUCTOR DEVICE INCLUDING A THROUGH SILICON VIA STRUCTURE
AND METHOD OF FABRICATING THE SAME**

the specification of which is attached hereto and identified as Attorney Docket No. 088453-8381.US00.

I made, authorized to make, or hereby make or authorize to make the above-identified patent application at the U.S. Patent and Trademark Office.

I have reviewed and understand the contents of the above-identified patent application including the claims.

I am aware of the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to patentability as defined in 37 CFR §1.56.

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I hereby acknowledge that any willful false statement made in the above declaration is punishable under 18 USC §1001 by fine or imprisonment of not more than five (5) years, or both.

ASSIGNMENT

I hereby assign to SK hynix Inc., a corporation of Republic of Korea, having a place of business at 2091, Gyeongchung-daero, Bubal-eub, Icheon-si, Gyeonggi-Do, Republic of Korea, and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in any and all inventions and improvements which are described in an application for United States Patent filed by me, entitled *SEMICONDUCTOR DEVICE INCLUDING A THROUGH SILICON VIA STRUCTURE AND METHOD OF FABRICATING THE SAME*, filed on March 31, 2021, and assigned U.S. Application Number 17/219,336. I authorize and request an attorney appointed in said application to hereafter insert above the filing date and application number of said application when known.

This assignment includes the entire right, title and interest in said application, all legal equivalents thereof in any country, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions and improvements, including, but not limited to, all divisions, continuations, reissues, reexamination certificates, any and all certificates issued in any post-grant proceeding, and extensions of said applications and patents of the United States, foreign patents, utility models, and design registrations, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes, and the right to seek relief and recover all damages, including, but not limited to, a reasonable royalty, by reason of infringement or any other violation of patent or patent application rights. I authorize the Assignee to apply in all countries in my name or in the name of the Assignee for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements.

In addition, I hereby confirm the sale, assignment, and transfer to the Assignee of the entire right, title and interest throughout the world in said inventions and improvements that

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occurred by operation of an employment agreement between me and the Assignee existing at the time said inventions and improvements were made. Should I have any remaining interest, I hereby sell, assign, and transfer any right, title and interest I may have in said inventions and improvements anywhere in the world to the Assignee.

The foregoing assignments, sale and transfer have been made for good and valuable consideration, the receipt of which is hereby acknowledged.

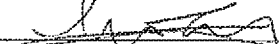
I hereby represent and covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into that would conflict with the assignment of said inventions and improvements to the Assignee.

I further covenant for myself and my respective heirs, legal representatives and assigns, to assist the Assignee in handling various procedures, tasks and documentation in connection with this assignment, including, but not limited to, providing to the Assignee promptly upon the request of the Assignee all pertinent facts and documents relating to said invention and improvements, and said patents, said legal equivalents or other legal instrument as may be known and accessible to me and testifying as to the same in any interference, litigation, or proceeding relating thereto, and promptly executing and delivering to the Assignee or its legal representative any and all papers, documents, instruments or affidavits in connection with obtaining, maintaining, issuing or enforcing said application, said inventions and improvements, and said patents, said equivalents and other legal instrument which may be necessary or desirable to carry out the purposes thereof.

I hereby authorize and request the Commissioner of Patents and Trademarks to issue one or more patents in the United States for said inventions and improvements to SK hynix Inc. as assignee of the entire interest, for the sole use and benefit of Assignee, its successors and assigns.

I am competent to execute the above declaration and assignment. I hereby have duly executed the declaration and assignment below with my name.

Full name of inventor: Jung Yong CHAE

Inventor's signature:  _____

Date: March 19, 2021 _____

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Full name of inventor: Jin Hee CHO

Inventor's signature:  _____

Date: March 19, 2021

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